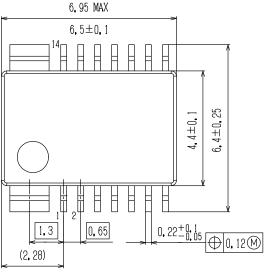
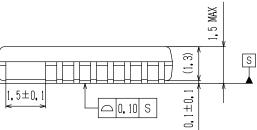
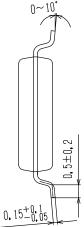


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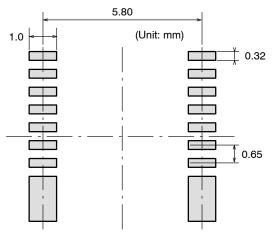




DATE 23 OCT 2013



SOLDERING FOOTPRINT*

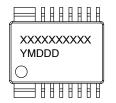


NOTES: 1. The measurements are not to guarantee but for reference only.

2. Land pattern design in Fin area to be altered in response to customer's individual application.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code

Y = Year

M = Month

DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

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0	RELEASED FOR PRODUCTION FROM SANYO ENACT# S-283 TO ON SEMICONDUCTOR. REQ. BY D. TRUHITTE.	30 NOV 2011		
А	ADDED MARKING AND SOLDER FOOTPRINT INFORMATION. REQUESTED BY D. TRUHITTE.	23 OCT 2013		

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